

Quarterly Reliability Monitoring Results

Quarters: Q1/2023 to Q4/2024

Based on structural similarity

| Supplier | | User Part Number | | | | |
|------------------------|--|---|-----------------------------------|-----------|------------|-----------|
| Nexperia B.V. | | PUSB3F97 | | | | |
| Name of Laboratory | | Part Description | | | | |
| Nexperia ATGD | | NXP ICN8 MCD package, Subcon UTAC Protection INDI | | | | |
| Based on AEC-Q101 Test | | Test Conditions | Duration | # Lots | # Quantity | # Rejects |
| # 1 | TEST Pre- and Post-Stress Electrical Test | Tamb = 25 °C | N/A | see below | all parts | see below |
| # 2 | PC Preconditioning | JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85% Reflow soldering | 24 hours 168 hours 3 cycles | 72 | 2880 | 0 |
| # 5 | HTRB High Temperature Reverse Bias | MIL-STD-750-1 M1038 Method A Tj = Tjmax, Vr = 100% of max. datasheet reverse voltage | 1000 hours | 38 | 1520 | 0 |
| # 7 | TC Temperature Cycling | JESD22-A104 -65 °C to Tjmax, not to exceed 150°C | 1000 cycles | 24 | 960 | 0 |
| # 8 or | UHAST Unbiased HAST | JESD22-A118 Tamb = 130 °C, RH = 85 % | 96 hours | 24 | 960 | 0 |
| # 8a | AC Autoclave | JESD22-A102 Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia) | | | | |
| # 9 | H3TRB High Humidity High Temperature Reverse Bias | JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of rated reverse voltage ^[1] | 1000 hours | 24 | 960 | 0 |
| # 10 | IOL Intermittent Operating Life | MIL-STD-750 Method 1037 ton = toff, devices powered to insure ΔTj = 100 °C for 15000 cycles | 1000 hours | n.a. | n.a. | n.a. |
| # 20 | RSH Resistance to Solder Heat | JESD22-A111 260 °C ± 5 °C | 10 s | n.a. | n.a. | 0 |
| # 21 | SD Solderability | J-STD-002 | | 22 | 660 | 0 |

[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1)

Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| Wafer Fab | Technology | Quantity | Rejects | Failure Rate (FIT) | MTTF (hrs) |
|-----------|-----------------|----------|---------|--------------------|------------|
| NXP ICN8 | Protection INDI | 1520 | 0 | 2,79 | 3,58E+08 |

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